



Features:

- For Surface Mounted Applications
- Low Profile Package
- Built-In Strain Relief
- Metal Silicon Junction, Majority Carrier Conduction
- High Surge Capability
- Low Power Loss, High Efficiency
- For Use In Low Voltage High Frequency Inverters, Free Wheeling And Polarity Protection Applications
- Guard Ring For Over Voltage Protection
- High Temperature Soldering Guaranteed : 250°C/10 Seconds At Terminals

Mechanical Data

- Case: JEDEC SMA, molded plastic over passivated chip
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Colour band denotes cathode end
- Weight : 0.002oz, 0.064g

Maximum Ratings and Thermal Characteristics

Ratings at 25°C ambient temperature unless otherwise specified

| Characteristic | Symbol | B230A-13-F | B240A-13-F | B260A-13-F | Units |
|---|-----------------|-------------|------------|------------|-------|
| Maximum repetitive peak reverse voltage | V_{RRM} | 30 | 40 | 60 | V |
| Maximum RMS voltage | V_{RWS} | 21 | 28 | 42 | V |
| Maximum DC blocking voltage | V_{DC} | 30 | 40 | 50 | V |
| Maximum average forward rectified current at T_L = See Fig. 1 | $I_{F(AV)}$ | 2 | | | A |
| Peak forward surge current 8.3ms single half-sine-wave | I_{FSM} | 50 | | | A |
| Maximum instantaneous forward voltage at 2A (Note 1) | V_F | 0.5 | | 0.7 | V |
| Maximum DC reverse current at $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=100^\circ\text{C}$ (Note 1) | I_R | 0.5 20 | | | mA |
| Typical thermal resistance (Note 2) | $R_{\theta JL}$ | 15 | | | °C/W |
| Operating junction and storage temperature range | T_J, T_{STG} | -55 to +125 | | | °C |

Notes:

- (1) Pulse test : 300µS pulse width, 1% duty cycle.
- (2) PCB mounted with 0.55" × 0.55" (14 × 14mm²) copper pad areas.

FIG.1 – FORWARD DERATING CURVE

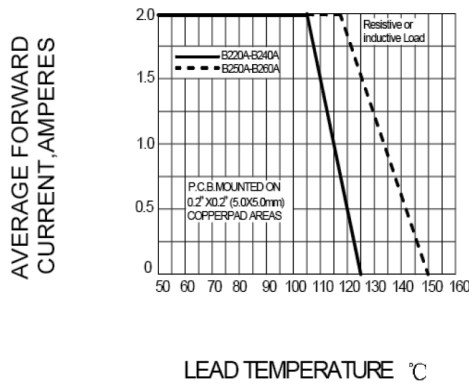


FIG.2- PEAK FORWARD SURGE CURRENT

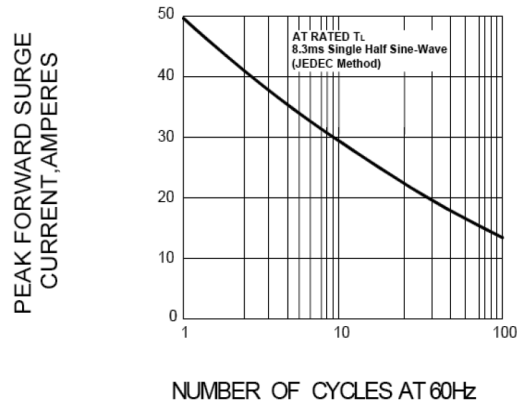


FIG.3 – TYPICAL FORWARD CHARACTERISTICS

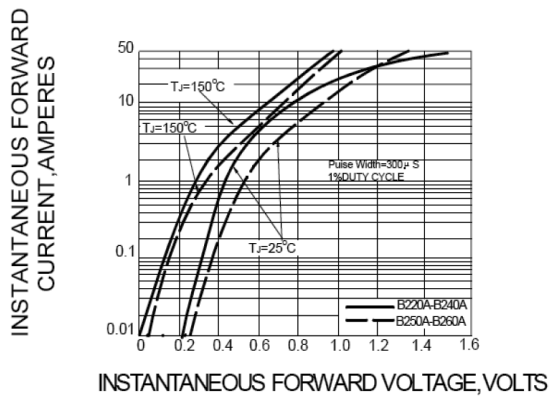


FIG.4 – TYPICAL REVERSE CHARACTERISTICS

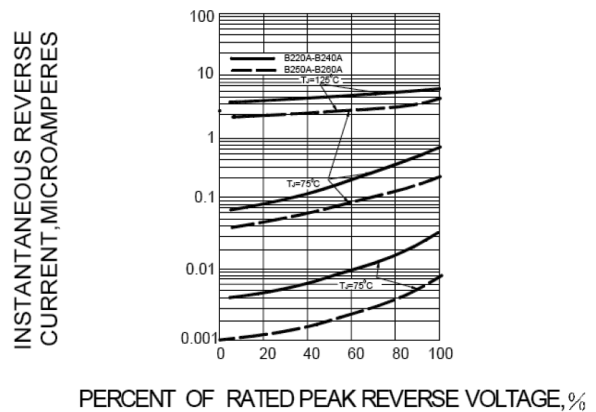
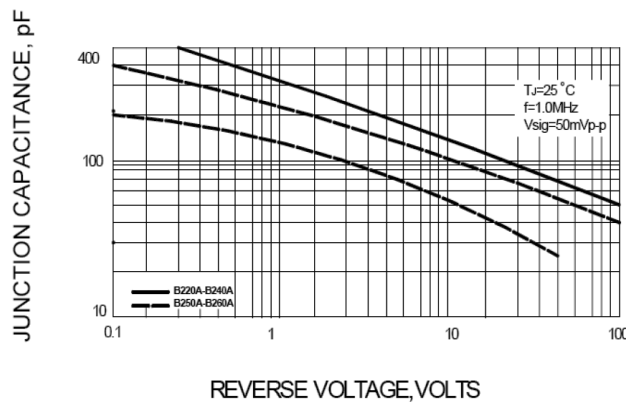
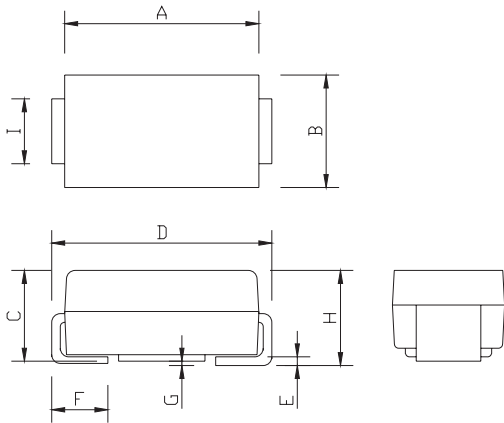


FIG.5-TYPICAL JUNCTION CAPACITANCE



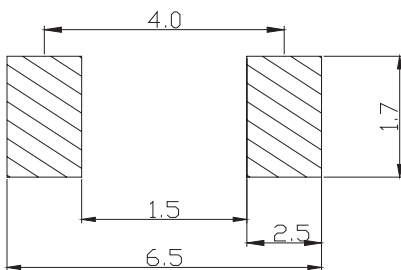
Package Outline Dimensions



| DO-214AC(SMA) | | |
|---------------|----------|------|
| Dim. | Min. | Max. |
| A | 4.25 | 4.65 |
| B | 2.4 | 2.8 |
| C | 1.85 | 2.15 |
| D | 4.85 | 5.35 |
| E | 0.2 Typ. | |
| F | 0.9 | 1.5 |
| G | 0.2 Max. | |
| H | 1.9 | 2.3 |
| I | 1.35 | 1.65 |

Dimensions : Millimetres

Soldering Footprint



Dimensions : Millimetres

Package Information

| Device | Package | Shipping |
|--|---------------|---------------------|
| B230A-13-F B240A-13-F B260A-13-F | DO-214AC(SMA) | 5,000 / Tape & Reel |

Part Number Table

| Description | Part Number |
|----------------------------|-------------|
| Schottky Barrier Rectifier | B230A-13-F |
| | B240A-13-F |
| | B260A-13-F |

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